

IEEE Tokyo Section Educational Activities Committee (EAC) presents

# 5G & Beyond The 'Insider' Story

## Key Information

When? Dec 19, 11:00 AM  
Where? Online (Zoom)  
How to register? [tinyurl.com/TokyoEA](https://tinyurl.com/TokyoEA)  
Registration deadline? Dec 18, 18:00 PM



**Yufei  
Blankenship**

Yufei Blankenship is currently a Principal Researcher with Ericsson. She has been actively participating in physical layer standardization with many years of experience in 3GPP. Her work spans numerous technical areas in 4G LTE and 5G NR, including channel coding, carrier aggregation, Machine Type Communication (MTC), Industry IoT (IIoT) and Ultra-Reliable Low Latency Communications (URLLC). She is the (co-)inventor of close to 200 issued US patents, and received the Ericsson Inventor of the Year award in 2020. She holds a Ph.D. degree of Electrical Engineering from Virginia Tech, Virginia, USA.



**Ajit  
Nimbalker**

Ajit Nimbalker is a Standardization Researcher at Ericsson since 2018 and works on physical layer standardization in 3GPP. Prior to Ericsson, Ajit was at Intel, contributing to 5G NR standardization, prototyping, algorithm development, and pre-standards work including 5GTF and 5G-SIG. He started his career in 2005 at Motorola working on research, development, and standardization for LTE and Wi-Fi. He has over 100 issued patents and holds a Ph.D. in Electrical Engineering from University of Notre Dame, Indiana, USA.

Host & moderator: Prakash Chaki, NEC, past delegate at 3GPP RAN1.

You may have heard academic notions of 5G and 6G. Have you wondered how these standards are really developed? Who are the faces working day in and day out behind the scenes?

Not the usual academic rhetoric. Come join us in this candid session to know first hand from the horse's mouth how the technology used in your latest smartphone was decided. Additionally, listen to the never-heard-before insiders' anecdotes from those who were in the room when 5G was drafted.

Ask them anything about technology, their career choices, or what keeps them going.

For inquiries, write to  
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\*This event will be held in English

This event is delightfully co-sponsored and partnered by

IEEE Tokyo Shin-etsu Joint Section Women In Engineering (WIE), IEEE Tokyo Section Life Members' Affinity Group (LMAG), IEEE Tokyo Section Young Professionals (YP), IEEE Tokyo Section Students' Activities Committee (SAC), IEEE Sendai Section Young Professionals (YP), IEEE Kansai Section Young Professionals (YP), IEEE Sapporo Section Young Professionals (YP), IEEE Japan Council Educational Activities (EA) Committee